

### Electronic Patent Application Fee Transmittal

Application Number:	10550153
Filing Date:	20-Sep-2005
Title of Invention:	Method for Analyzing Copper Electroplating Solution, Apparatus for the Analysis, and Method for Fabricating Semiconductor Product
First Named Inventor/Applicant Name:	Toshikazu Okubo
Filer:	Cameron Kerrigan/Mary Padilla
Attorney Docket Number:	38915.00045

Filed as Large Entity

#### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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**Basic Filing:**

**Pages:**

**Claims:**

Claims in excess of 20	1615	4	52	208
Independent claims in excess of 3	1614	4	220	880

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

**Post-Allowance-and-Post-Issuance:**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1088</b>